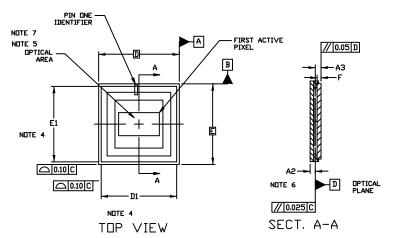


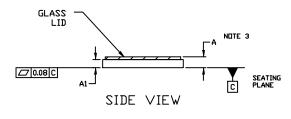
## PLCC48 11.43x11.43 (HiSPi) CASE 776AQ **ISSUE E**

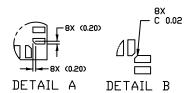
**DATE 20 NOV 2017** 



## NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
- 4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.
- MAXIMUM ROTATION OF OPTICAL AREA RELATIVE D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.
- 6. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
- OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X= 275 MICRONS, Y= 0 MICRONS ±75 MICRONS.
- 8. SOLDER MASK OPENINGS FOR THERMAL CONNECTION PADS.

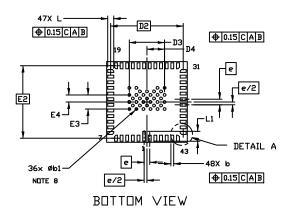


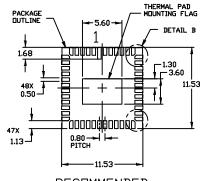


Α	1.36	1.71
A1	1.15 REF	
A2	0.65 0.80	
A3	0.71	0.91
b	0.35	0.45
b1	0.40 REF	
D	11.43 BSC	
D1	10.65	10.75
D2	10.28 BSC	
DЗ	5.00 REF	
D4	2.00 REF	
Ε	11.43 BSC	
E1	10.65	10.75
E2	10.28 BSC	
E3	2.50 REF	
E4	1.00 REF	
e	0.80 BSC	
F	0.50	0.60
L	0.80	0.90
L1	1.35	1.45

MILLIMETERS

DIM MIN. MAX.





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DESCRIPTION:	PLCC48 11.43X11.43 (HiSPi)		PAGE 1 OF 2



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98AON99907	'F

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ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION FROM APTINA POD# AR0237 TO ON SEMICONDUCTOR. REQ. BY D. TRUHITTE.	07 JUL 2015
Α	UPDATED ACTIVE ARRAY AND PINOUT TABLE. REQ. BY M. FORBIS.	20 NOV 2015
В	MODIFIED COVER GLASS TILT AND DIE TOLERANCE. REQ. BY S. YIP.	03 FEB 2016
С	MODIFIED DRAWING TO JEDEC STANDARD FORMAT. REQ. BY M. FORBIS.	22 JUN 2016
D	ADDED HISPI TO TITLE. DRAWING UPDATED TO INCLUDE LATEST DEFINITIONS. REQ. BY M. FORBIS.	24 OCT 2017
E	REVISED DIMENSIONS A AND A3. REQ. BY M. FORBIS.	20 NOV 2017

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